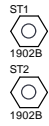
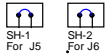
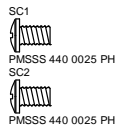
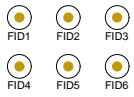


PCB Number: TIDA-01400  
PCB Rev: A

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PCB  
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Pb-Free Symbol

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ZZ1  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

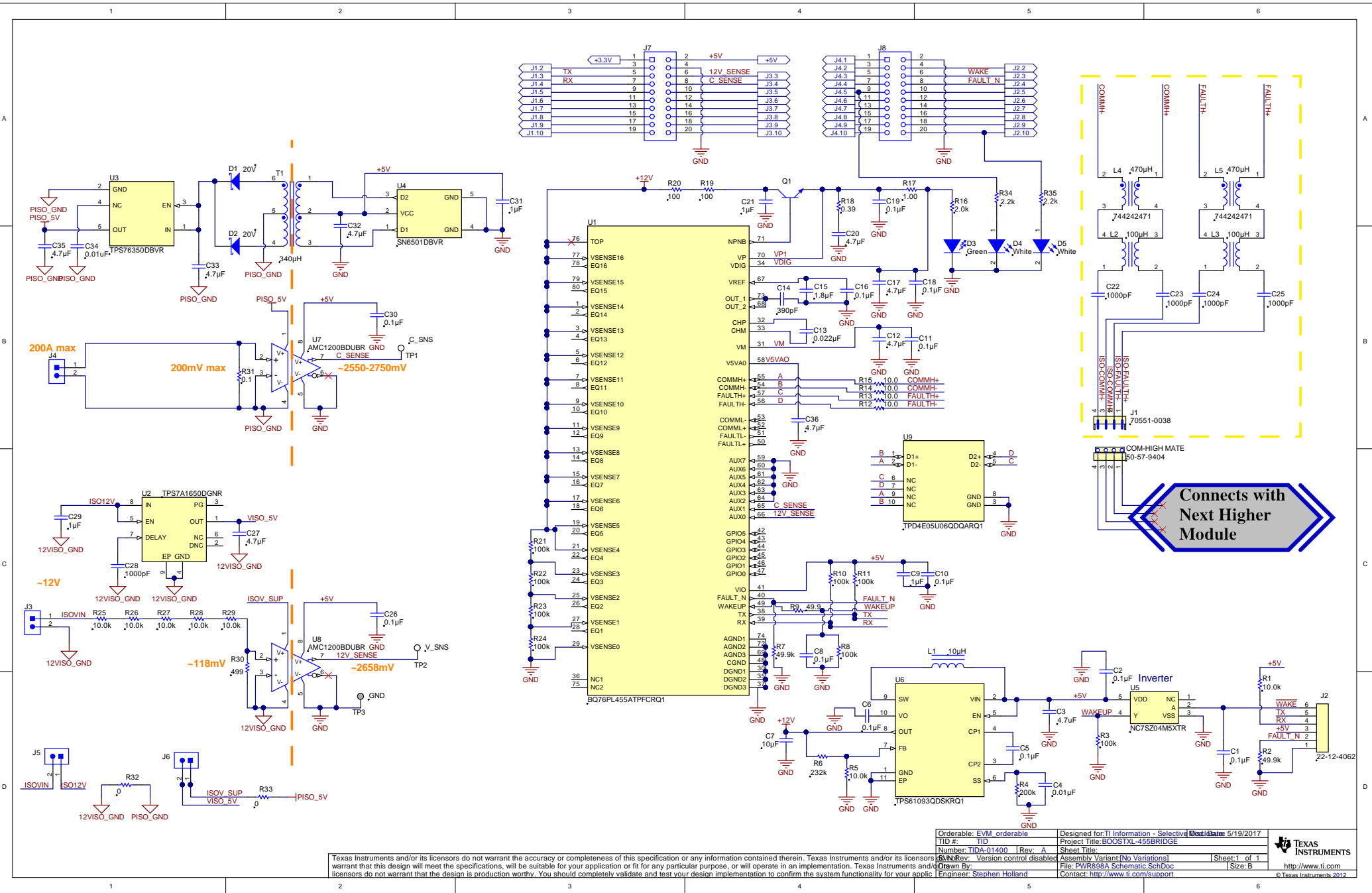
ZZ3  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ4  
**Assembly Note**  
Screws SC1 and SC2 are for Standoffs ST1 and ST2

Orderable: EVM, orderable	Designed for: TI Information - Selective Declass 3/17/2017
TID #: TID	Project Title: BOCSTXL-455BRIDGE
Number: TIDA-01400   Rev: A	Sheet Title:
Rev: Version control disabled	Assembly Variant[No Variations]
Drawn By:	File: PWR898A Hardware_SchDoc
Engineer: Stephen Holland	Contact: http://www.ti.com/support

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 Engineer: Stephen Holland

Orderable: EVM, orderable	Designed for: TI Information - Selective Doc	Date: 5/19/2017	 <a href="http://www.ti.com">http://www.ti.com</a>
TID #: TID	Project File: BOCSTXL-455BRIDGE		
Number: TIDA-01400   Rev: A	Sheet Title:	Sheet: 1 of 1	
Assembly Variant: [No Variations]	File: PWR988A Schematic_SchDoc	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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